

ABSTRACT

The invention provides an adhesive tape which acts as a dicing tape which is excellent in dicing property and pickup property in a dicing step, and as an adhesive tape which is excellent in connection reliability in a step of bonding a semiconductor device with a supporting member. The adhesive film comprises a layer in which an adhesive layer (A) comprising an olefin polymer and an adhesive layer (B) are directly laminated to each other, wherein the 180° peel strength between the layer (A) and the layer (B) is not more than 0.7 N/10 mm.